

A02  
 $\phi$  4.0 A C

CENTER LINES OF OPTICAL CONNECTOR

NOTE 2

MEASUREMENT AIRFLOW DIRECTION

DETAIL B

A16

A17

A18

A19

A20

CENTER LINES OF OPTICAL CONNECTOR

NOTE.5

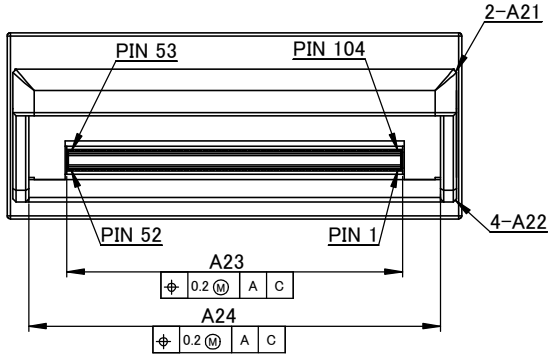
NOTE.6

r

B

f

MATING PLANE



DETAIL A  
 (CUTOUT FOR DATUM "-D-" INSPECTION)

DENT TO AVOID EMI-GASKET PROTECT OF COVER

MATING PLANE

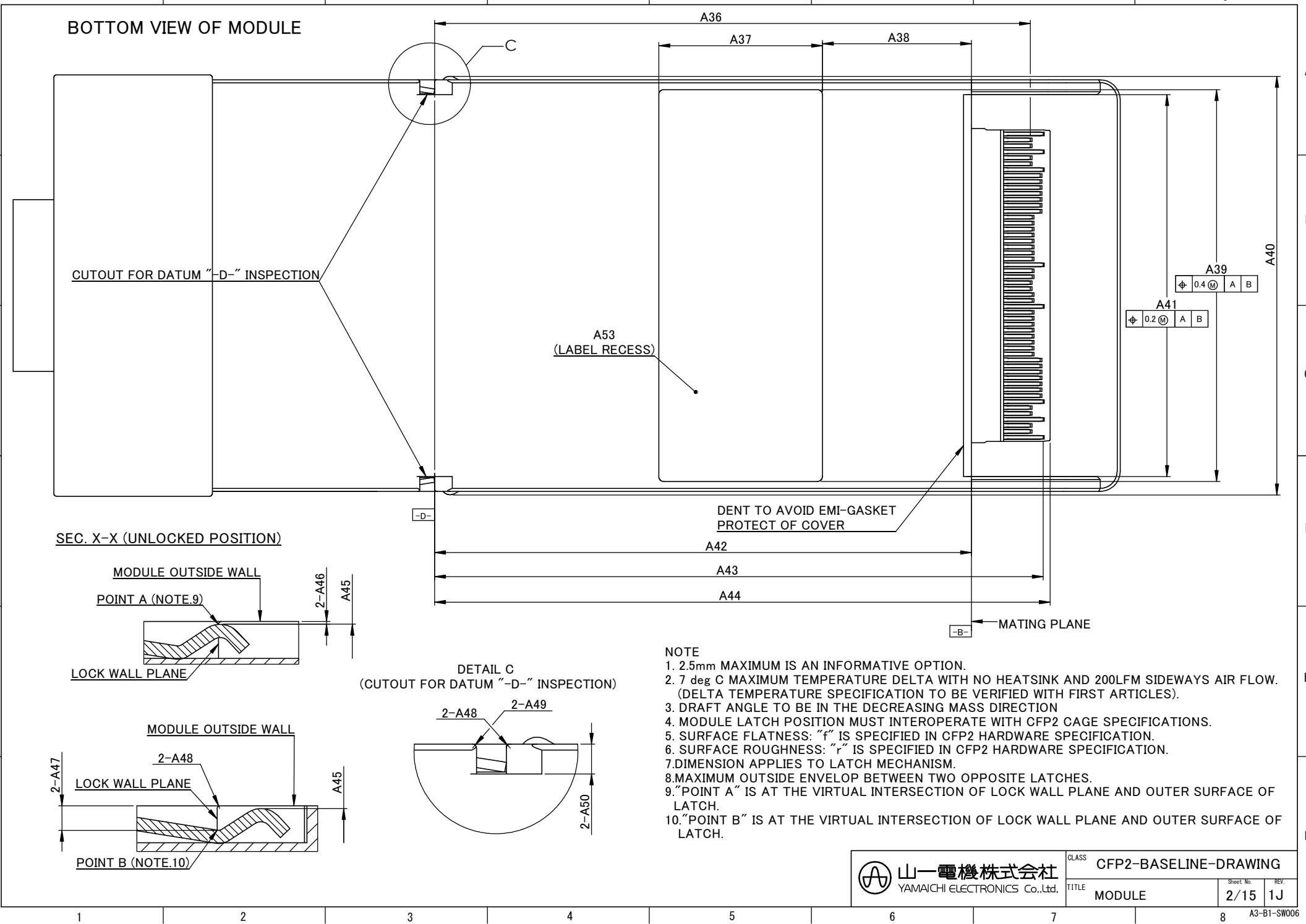
山一電機株式会社  
 YAMAICHI ELECTRONICS Co.,Ltd.

CLASS CFP2-BASELINE-DRAWING

TITLE MODULE

Sheet No. 1/15  
 REV. 1J

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**BOTTOM VIEW OF MODULE**

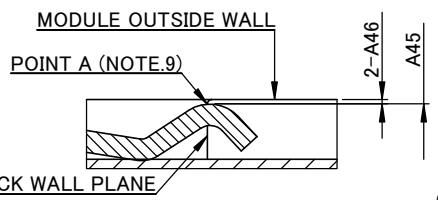
CUTOUT FOR DATUM "-D-" INSPECTION

A53  
(LABEL RECESS)

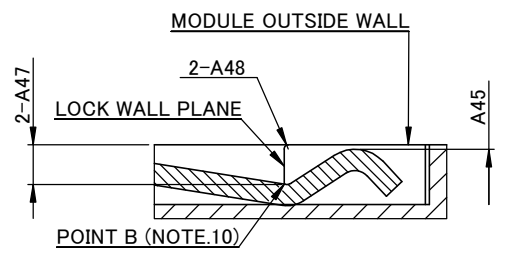
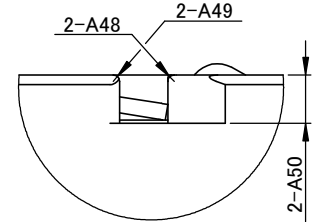
DENT TO AVOID EMI-GASKET  
PROTECT OF COVER

MATING PLANE

SEC. X-X (UNLOCKED POSITION)




DETAIL C (CUTOUT FOR DATUM "-D-" INSPECTION)



**NOTE**

1. 2.5mm MAXIMUM IS AN INFORMATIVE OPTION.
2. 7 deg C MAXIMUM TEMPERATURE DELTA WITH NO HEATSINK AND 200LFM SIDEWAYS AIR FLOW. (DELTA TEMPERATURE SPECIFICATION TO BE VERIFIED WITH FIRST ARTICLES).
3. DRAFT ANGLE TO BE IN THE DECREASING MASS DIRECTION
4. MODULE LATCH POSITION MUST INTEROPERATE WITH CFP2 CAGE SPECIFICATIONS.
5. SURFACE FLATNESS: "f" IS SPECIFIED IN CFP2 HARDWARE SPECIFICATION.
6. SURFACE ROUGHNESS: "r" IS SPECIFIED IN CFP2 HARDWARE SPECIFICATION.
7. DIMENSION APPLIES TO LATCH MECHANISM.
8. MAXIMUM OUTSIDE ENVELOP BETWEEN TWO OPPOSITE LATCHES.
9. "POINT A" IS AT THE VIRTUAL INTERSECTION OF LOCK WALL PLANE AND OUTER SURFACE OF LATCH.
10. "POINT B" IS AT THE VIRTUAL INTERSECTION OF LOCK WALL PLANE AND OUTER SURFACE OF LATCH.

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CFP2 MODULE DIMENSION

KEY	VALUE	TOLERANCE	DESCRIPTION
A01	42.50	MAX.	WIDTH OF MODULE FACEPLATE, OVERALL
A02	17.30	MAX.	OPTICAL CONNECTOR RECEPTACLE, OVERALL
A03	4.10	MAX.	OPTICAL CONNECTOR RECEPTACLE FROM MODULE FACEPLATE TOP FRONT SURFACE
A04	6.25	BASIC	CENTER LINES OF OPTICAL CONNECTOR
A05	5.525	BASIC	CENTER LINES TO SIDE OF OPTICAL CONNECTOR
A06	R2.00	±0.10	TOP MODULE LEAD-IN RADIUS
A07	41.50	±0.20(SEE NOTE 3)	WIDTH, MODULE BODY, OVERALL
A08	107.50	±0.20	LENGTH OF MODULE, OVERALL
A09	54.10	±0.10	LATCH POSITION FROM DATUM -B-
A10	12.40	±0.20	HEIGHT, MODULE BODY, OVERALL
A11	91.50	MIN.	HEIGHT OF MODULE TO OPTICAL CONNECTOR
A12	3.40	MAX.(SEE NOTE 1)	HEIGHT OF OPTICAL CONNECTOR ,TOP SIDE
A13	1.60	MAX.	HEIGHT OF OPTICAL CONNECTOR ,BOTTOM SIDE
A14	5.90	±1.50	CENTER LINES OF OPTICAL CONNECTOR
A15	2.50	MAX.(SEE NOTE 1)	HEIGHT OF OPTICAL CONNECTOR OF LOW PROFILE ,TOP SIDE
A16	R2.00	±0.20	TOP MODULE LEAD-IN RADIUS
A17	C0.30	±0.10	TOP OF MODULE CORNER
A18	2.00	±0.10	START OF SIDE WALL
A19	6.00	±0.20	END OF SIDE WALL
A20	R2.00	±0.10	SIDE WALL LEAD-IN RADIUS
A21	C0.30	±0.10	MODULE OUTSIDE CHAMFER OR RADIUS
A22	C0.30	±0.10	MODULE OUTSIDE CHAMFER OR RADIUS
A23	31.40	±0.04	WIDTH, CONNECTOR, OVERALL
A24	38.50	±0.10(SEE NOTE 3)	WIDTH, MODULE SIDEWALL, OVERALL
A25	8.05	±0.20	DISTANCE FROM DATUM -C- TO BOTTOM SURFACE OF MODULE TAIL
A26	3.90	±0.15	DATUM -C- TO CENTER LINE OF CONNECTOR
A27	15.00	±0.10	DISTANCE FROM DATUM -B- TO MODULE END
A28	7.95	REF.	LENGTH OF CONNECTOR END FROM DATUM -B-
A29	0.80	±0.10	DENT TO AVOID EMI-GASKET PROTECT OF COVER
A30	0.40	±0.10	DENT TO AVOID EMI-GASKET PROTECT OF COVER
A31	2.00	MIN.	WIDTH OF LATCH
A32	R0.30	±0.10	MODULE OUTSIDE WALL CORNER
A33	0.65	±0.15	MODULE OUTSIDE WALL SLOPE
A34	1.50	MAX.	WIDTH OF CUTOUT
A35	20deg	±10deg.	MODULE OUTSIDE WALL SLOPE
A36	60.05	±0.20	LENGTH OF CONNECTOR SIGNAL PIN FROM DATUM -D-
A37	16.50	MAX.	LABEL RECESS LENGTH
A38	15.00	±5.00	LABEL RECESS FROM DATUM -B-
A39	39.50	MAX.	LABEL RECESS WIDTH
A40	41.70	MAX.(SEE NOTE 8)	LATCH SURFACE
A41	38.40	MIN.	DENT TO AVOID EMI-GASKET PROTECT OF COVER
A42	54.10	REF.	LATCH POSITION FROM DATUM -B-
A43	61.35	±0.25	LENGTH OF CONNECTOR GND PIN FROM DATUM -D-
A44	62.05	±0.15	LENGTH OF CONNECTOR FROM DATUM -D-
A45	41.70	MAX.(SEE NOTE 7, 8)	LATCH SURFACE
A46	0.05	MAX.(SEE NOTE 7,9)	MODULE OUTSIDE WALL TO POINT A
A47	0.75	±0.20(SEE NOTE 7,10)	MODULE OUTSIDE WALL TO POINT B
A48	R0.10	+0.05/-0.10	LOCK WALL RADIUS
A49	R0.20	±0.10	CUTOUT OF INSPECTION WALL RADIUS
A50	1.40	REF.	MINIMUM CUTOUT FOR DATUM -D- INSPECTION
A51	9.80	MIN.	END OF LOCK WALL POSITION, TOP
A52	2.45	MAX.	END OF LOCK WALL POSITION, BOTTOM
A53	0.20	MAX.	LABEL RECESS DEPTH
A54	6.35	±0.30(SEE NOTE 7)	LATCH CENTER LINE FROM DATUM -C-

A

B

C

D

E

F

A


B

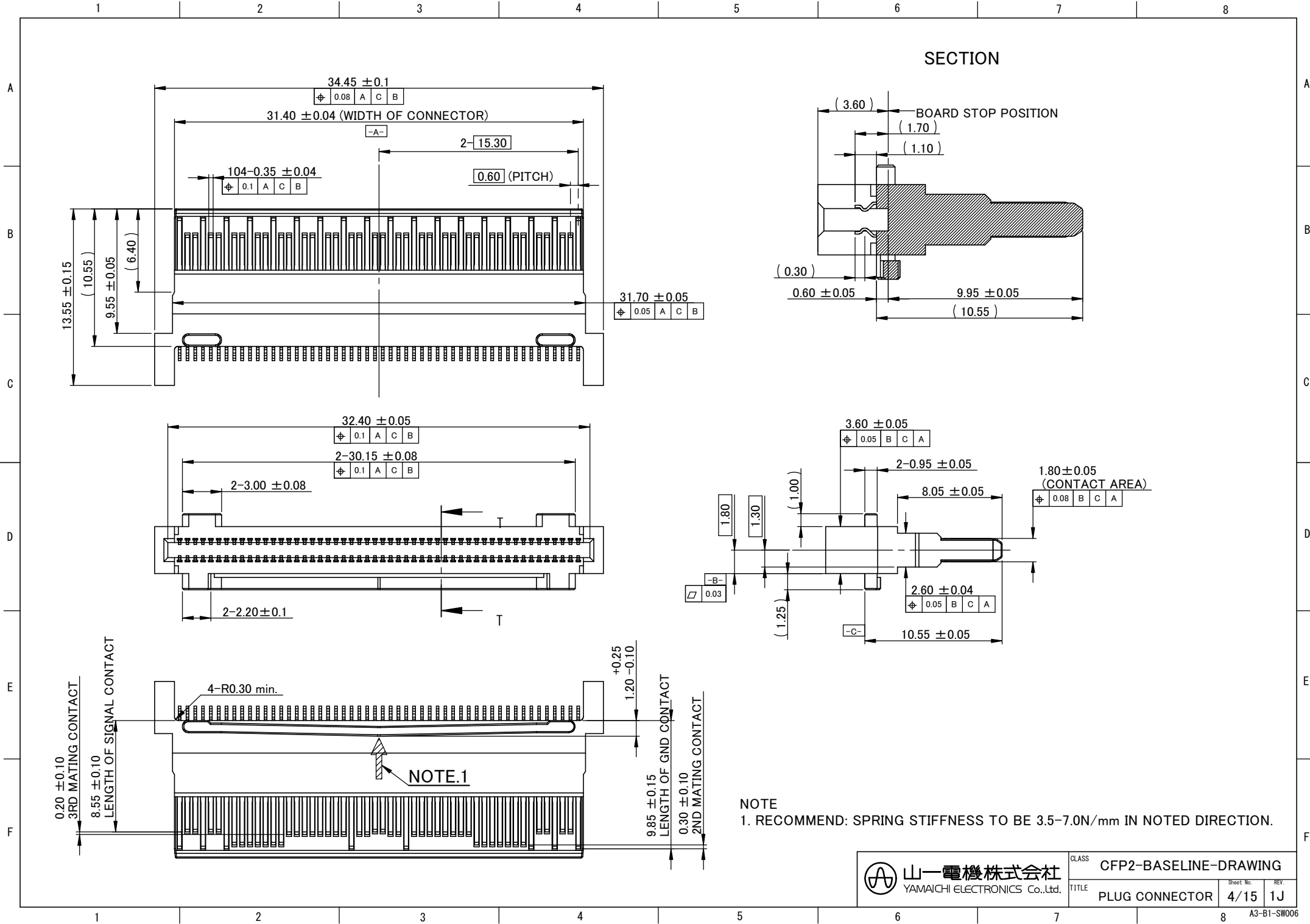
C

D

E

F

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	TITLE	MODULE	Sheet No. <b>3/15</b> REV. <b>1J</b>



1 2 3 4 5 6 7 8

A

A

B

B

C

C

D

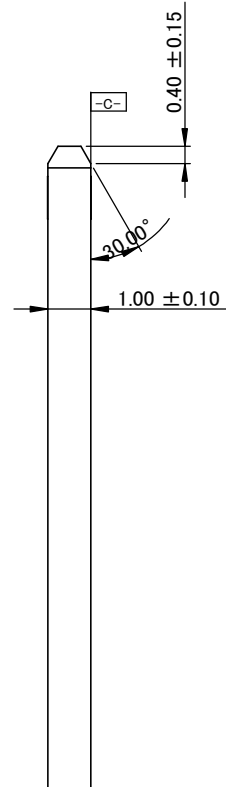
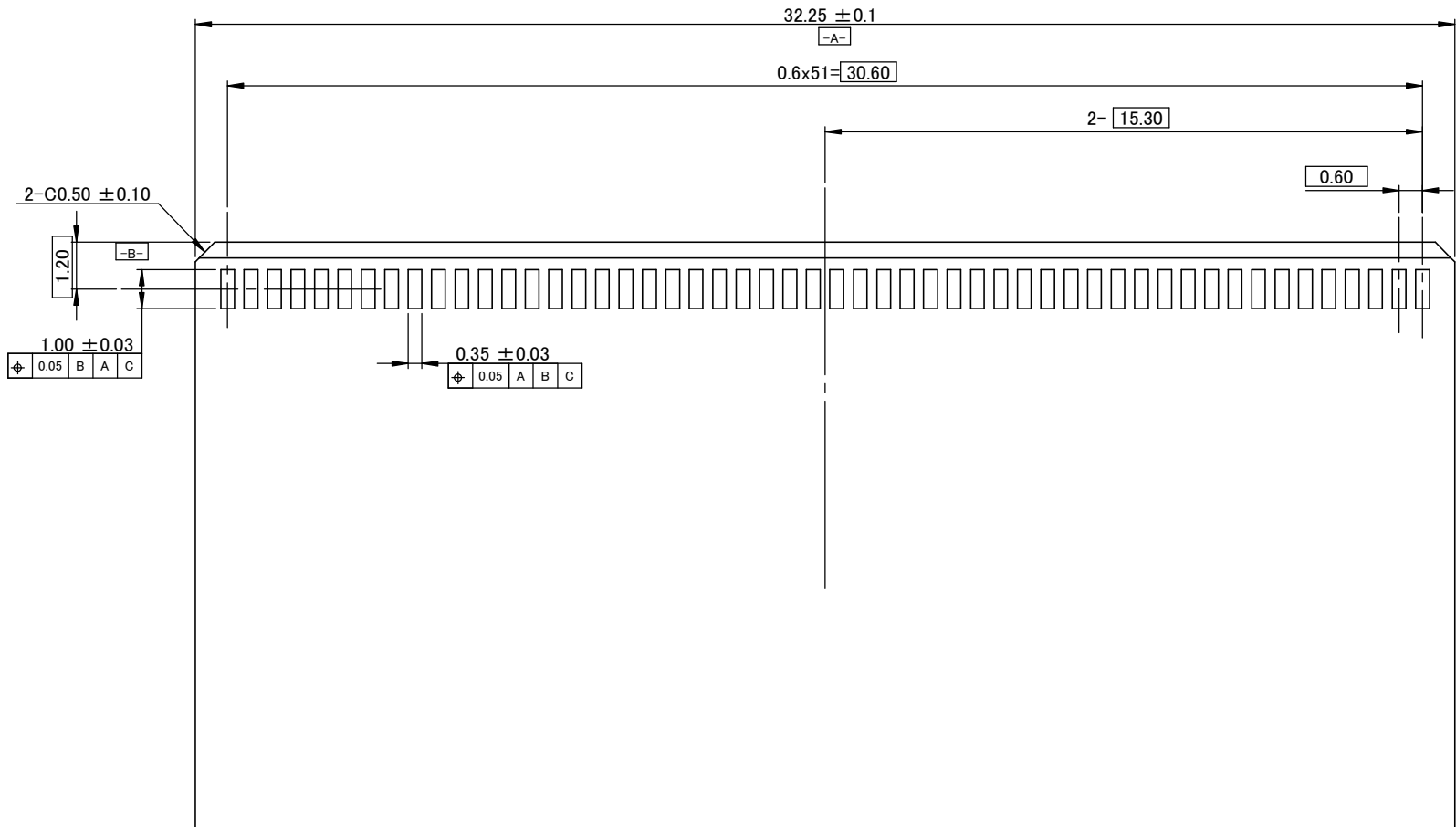
D


E

E

F

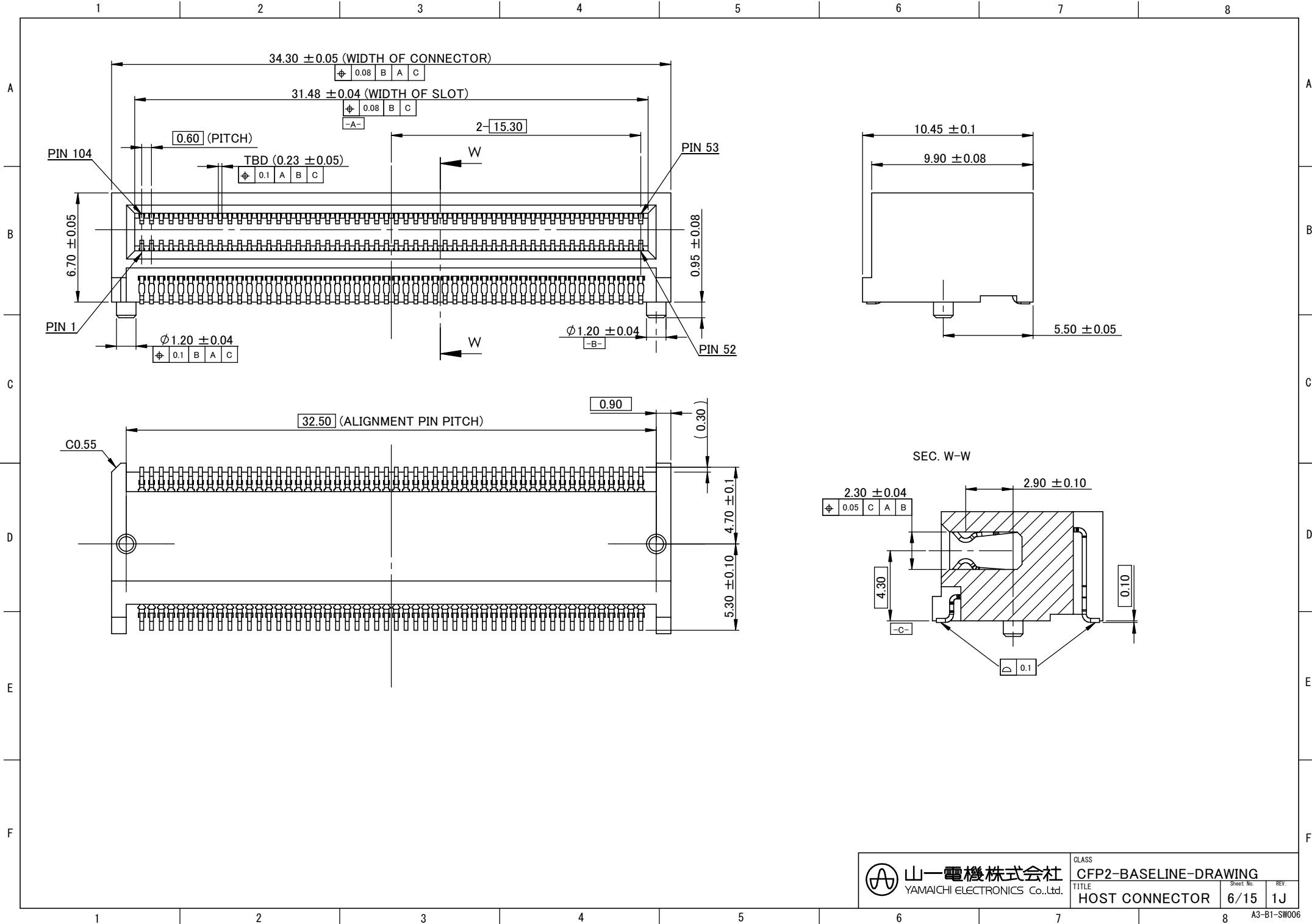
F

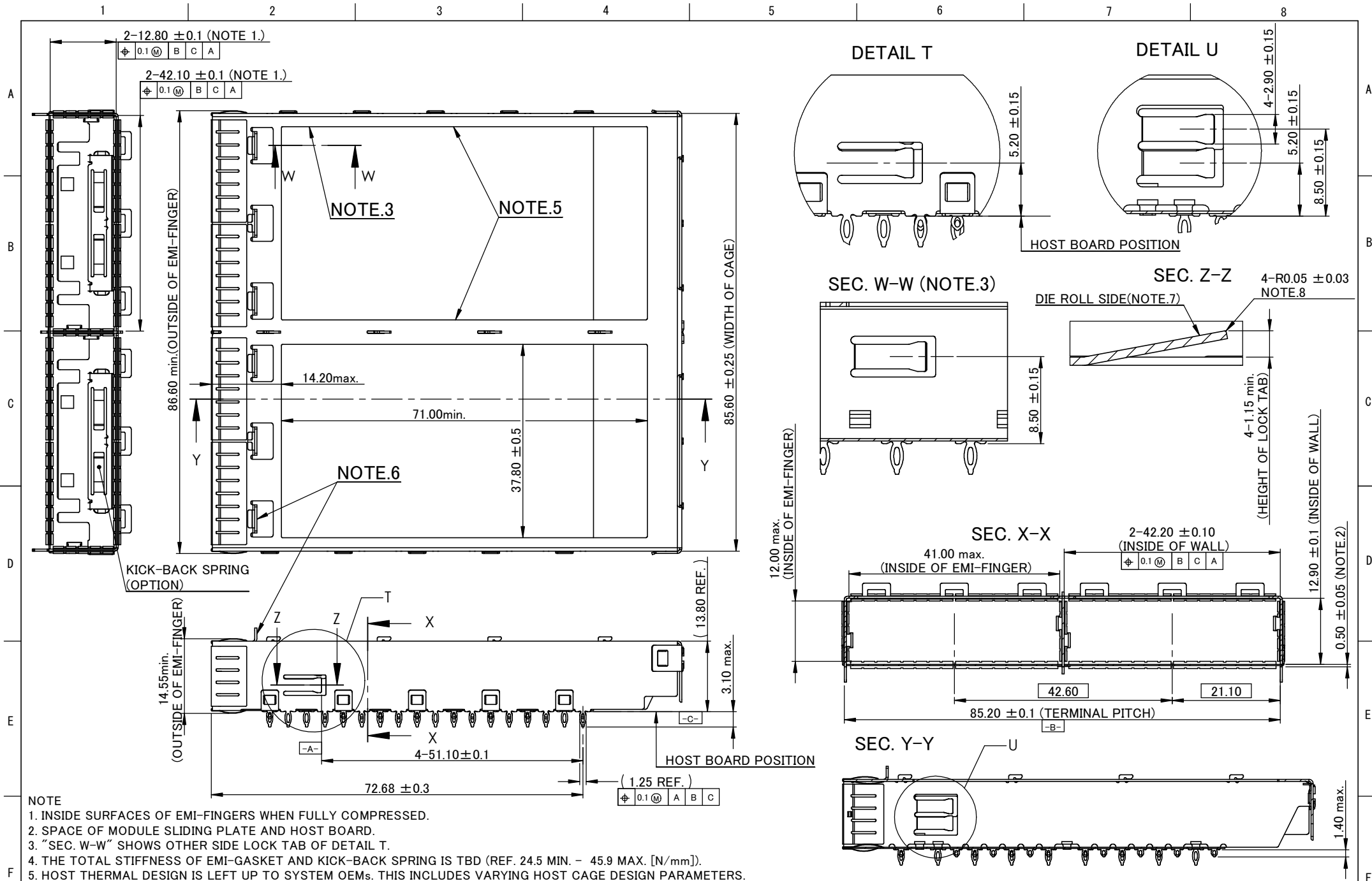


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	TITLE	MODULE BOARD	REV.
	Sheet No.	5/15	1J

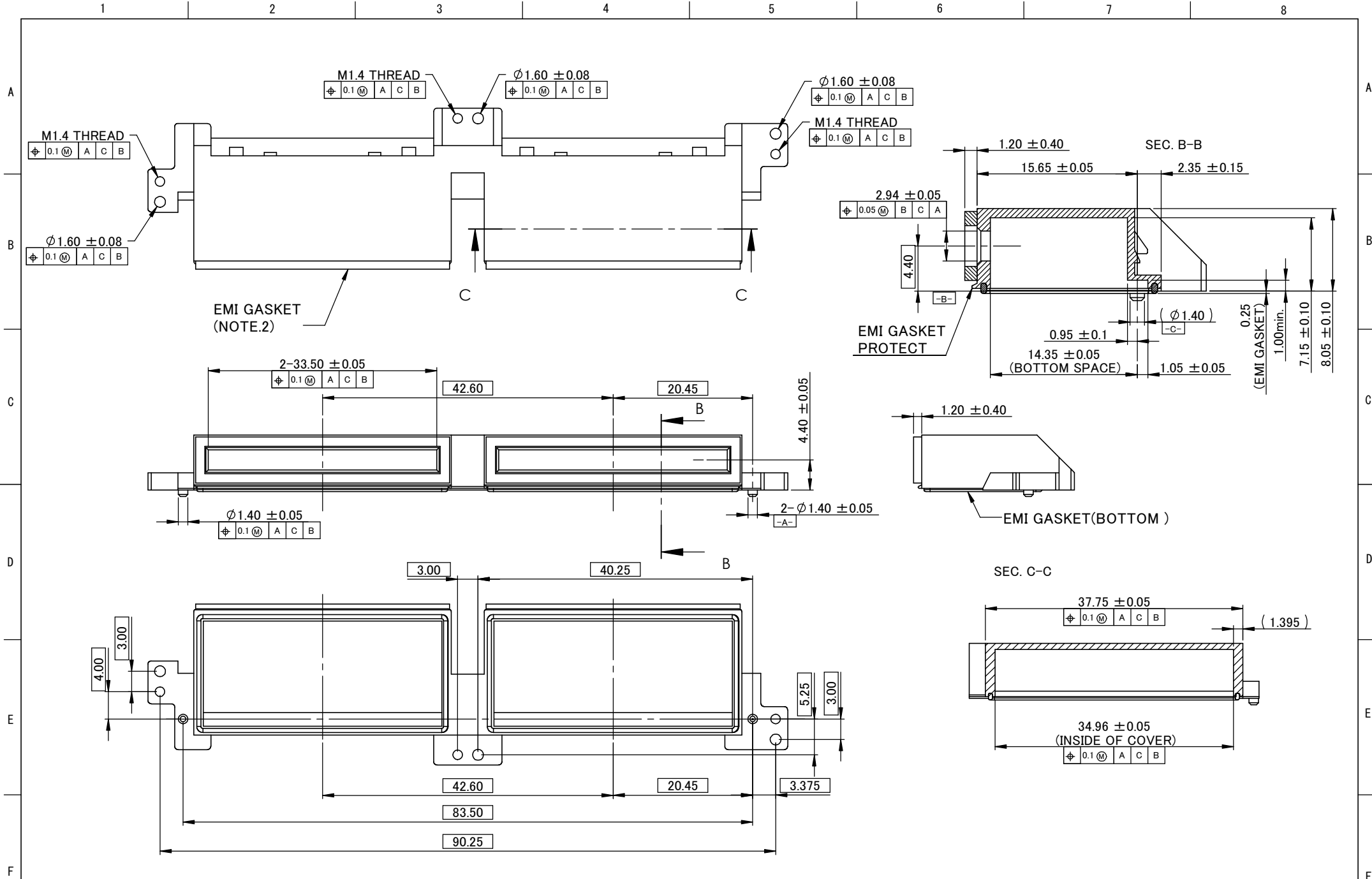
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1 2 3 4 5 6 7 8





- NOTE
1. INSIDE SURFACES OF EMI-FINGERS WHEN FULLY COMPRESSED.
  2. SPACE OF MODULE SLIDING PLATE AND HOST BOARD.
  3. "SEC. W-W" SHOWS OTHER SIDE LOCK TAB OF DETAIL T.
  4. THE TOTAL STIFFNESS OF EMI-GASKET AND KICK-BACK SPRING IS TBD (REF. 24.5 MIN. - 45.9 MAX. [N/mm]).
  5. HOST THERMAL DESIGN IS LEFT UP TO SYSTEM OEMs. THIS INCLUDES VARYING HOST CAGE DESIGN PARAMETERS.
  6. CAGE LOCK IS OPTIONAL. WITHOUT THE CAGE LOCK, A DIFFERENT HEATSINK DESIGN IS REQUIRED AS THE ONE SHOWN WILL NOT WORK.
  7. INSIDE OF CAGE SHOULD BE USED A DIE ROLL SIDE OF MATERIAL EXCEPT FOR ONE SIDE OF CENTER WALL.
  8. INSIDE OF TIP OF LOCK TAB SHOULD BE ADDED A RADIUS.
  9. INSERTION AND EXTRACTION FORCE OF CAGE TO HOST BOARD ARE 2000N MAXIMUM AND 400N MINIMUM.



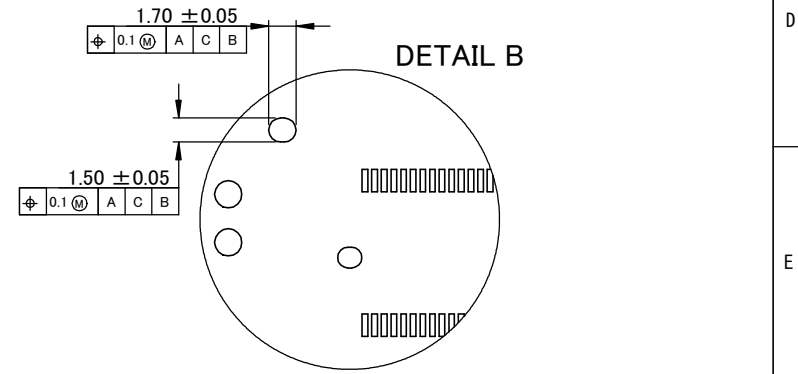
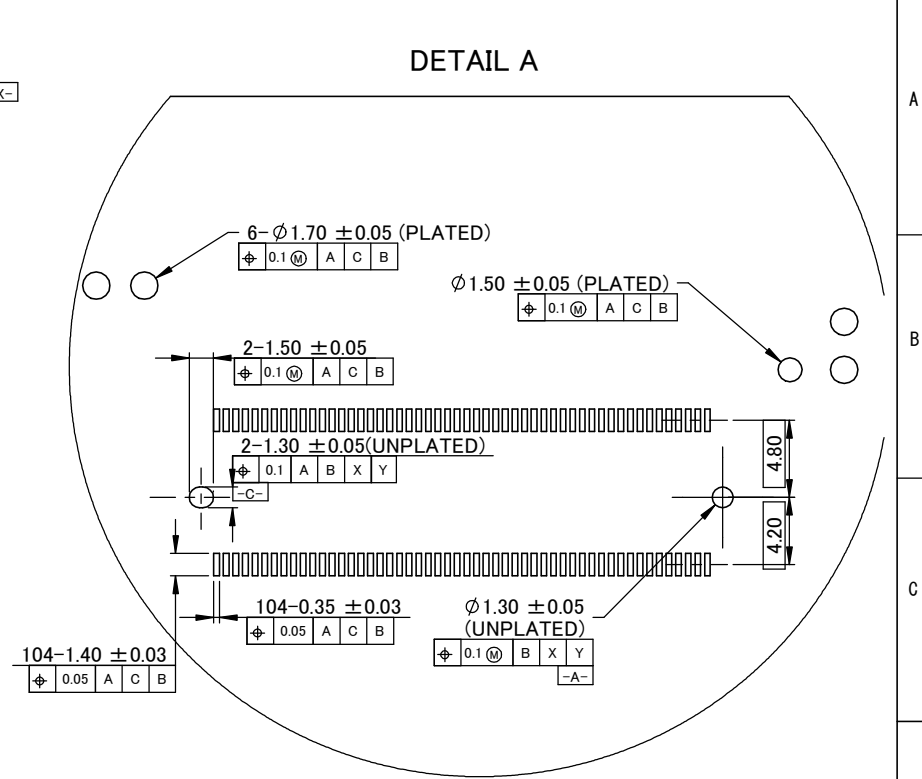
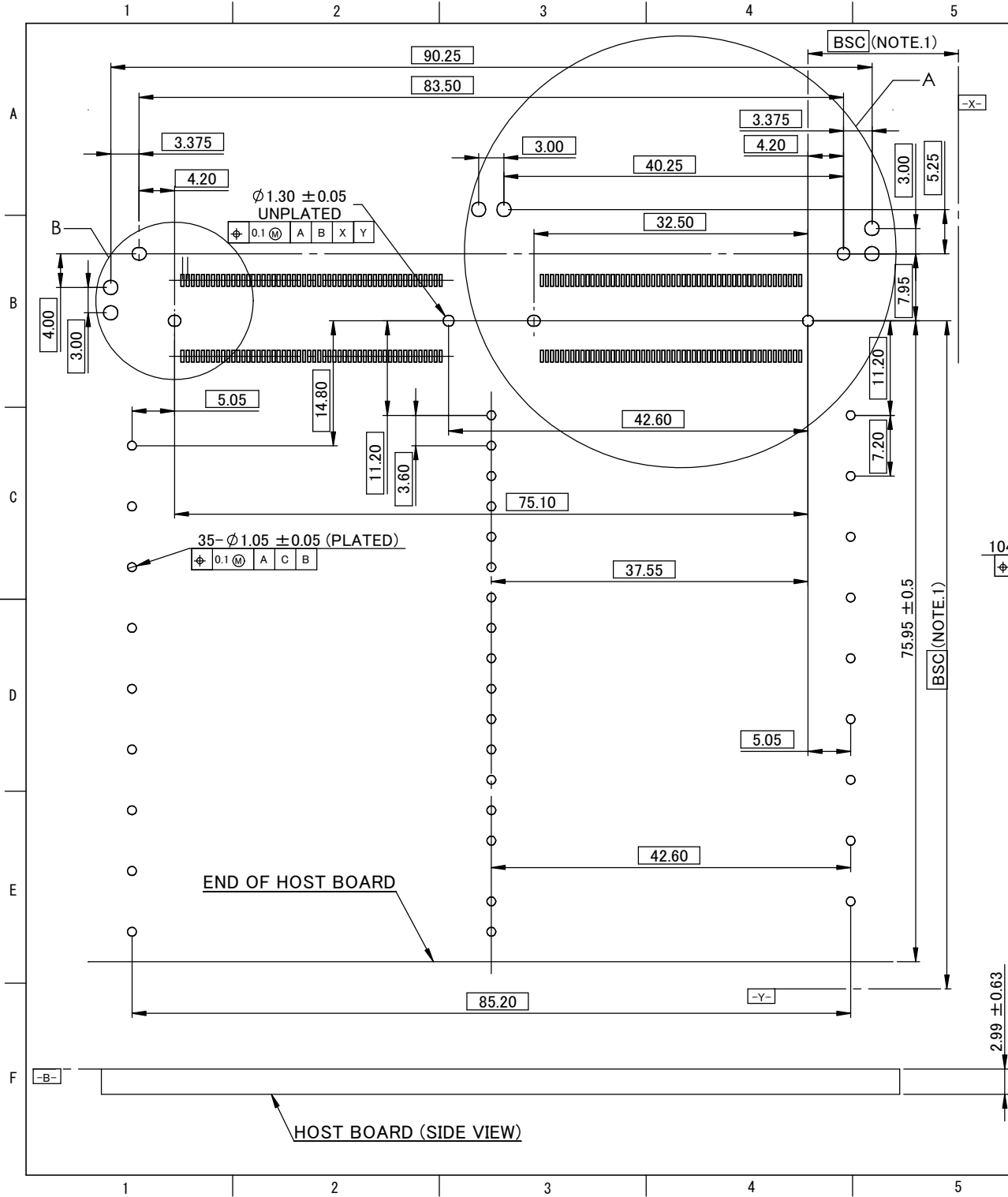
NOTE

1. MAXIMUM DELTA DEFLECTION OF HOST CONNECTOR COVER AFTER SCREW MOUNT ON HOST BOARD IS 0.02mm.
2. GASKET TO MEET MINIMUM PEEL STRENGTH SPECIFIED IN CFP2 HARDWARE SPECIFICATION.

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	TITLE	HOST CONNECTOR COVER	
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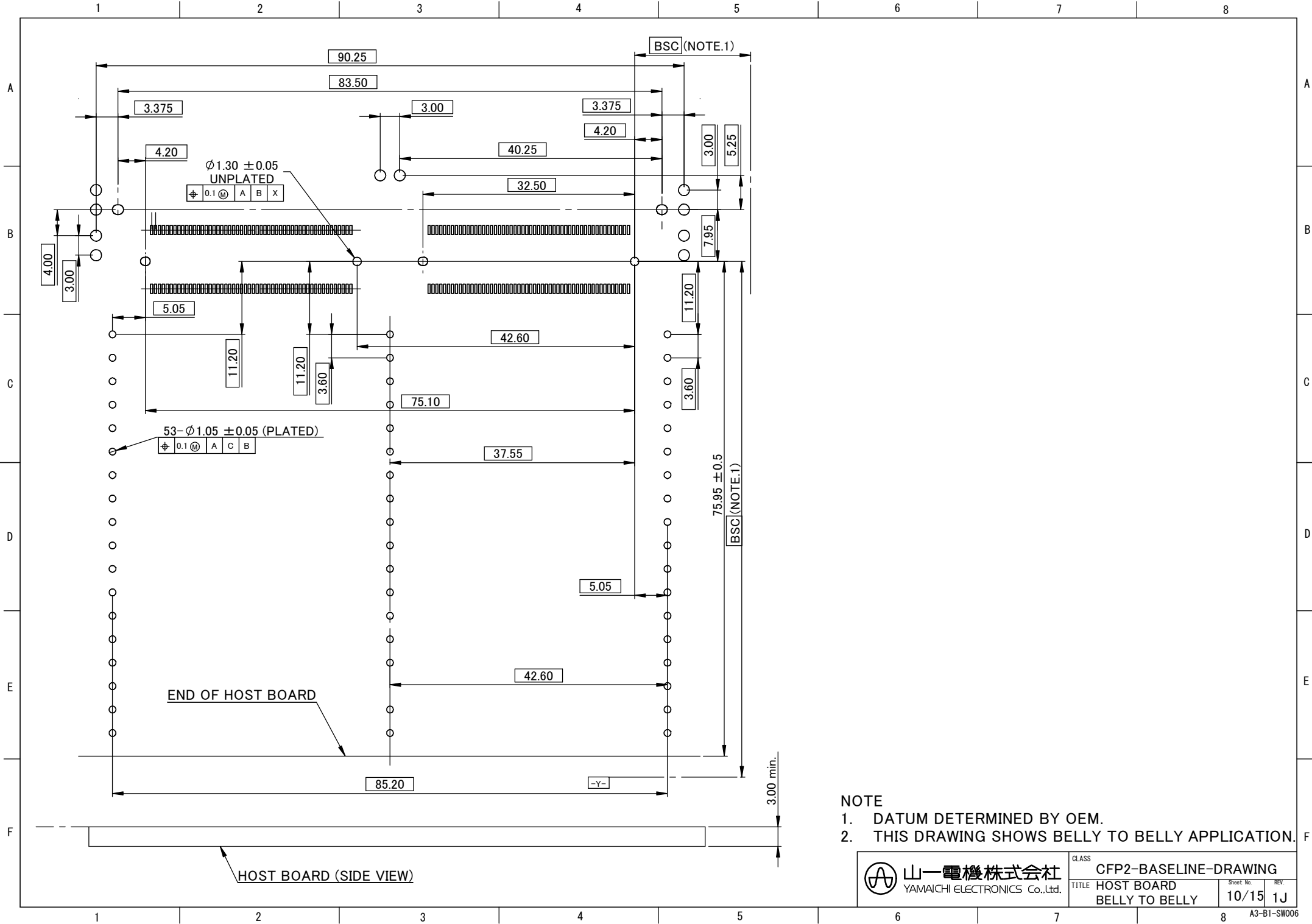


**NOTE**


- DATUM DETERMINED BY OEM.
- THIS DRAWING SHOWS SINGLE SIDE APPLICATION.

 山一電機株式会社 YAMAICHI ELECTRONICS Co.,Ltd.	CLASS	CFP2-BASELINE-DRAWING	
	TITLE	HOST BOARD SINGLE SIDE	Sheet No. 9/15 REV. 1J

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NOTE  
 1. DATUM DETERMINED BY OEM.  
 2. THIS DRAWING SHOWS BELLY TO BELLY APPLICATION.

 山一電機株式会社 YAMAICHI ELECTRONICS Co.,Ltd.	CLASS CFP2-BASELINE-DRAWING	
	TITLE HOST BOARD BELLY TO BELLY	Sheet No. 10/15 REV. 1J

1 2 3 4 5 6 7 8

A

B

C

D

E

F

A

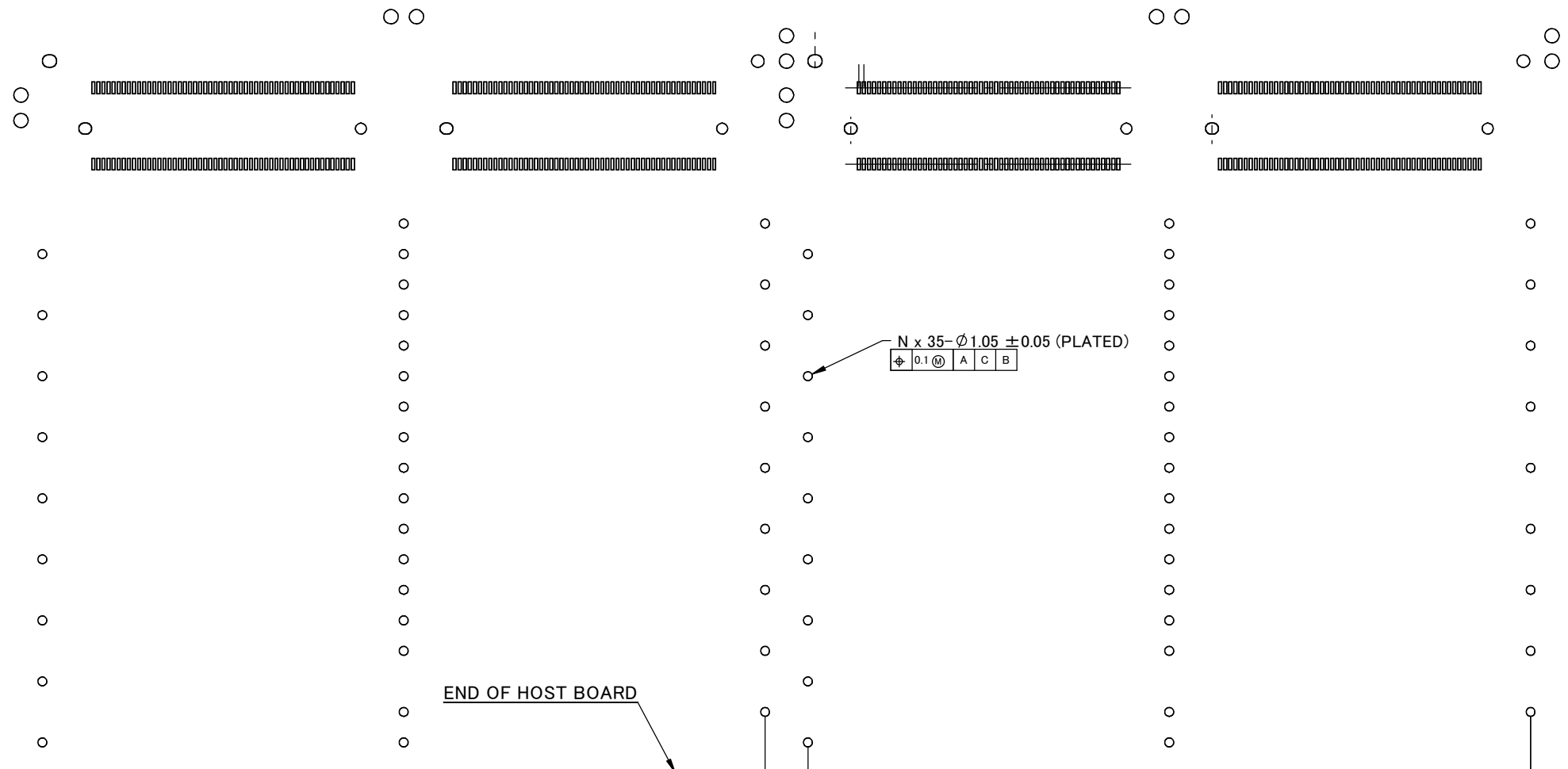
B

C

D

E

F



N x 35-Ø1.05 ± 0.05 (PLATED)

Ø	0.1	A	C	B
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END OF HOST BOARD

85.20

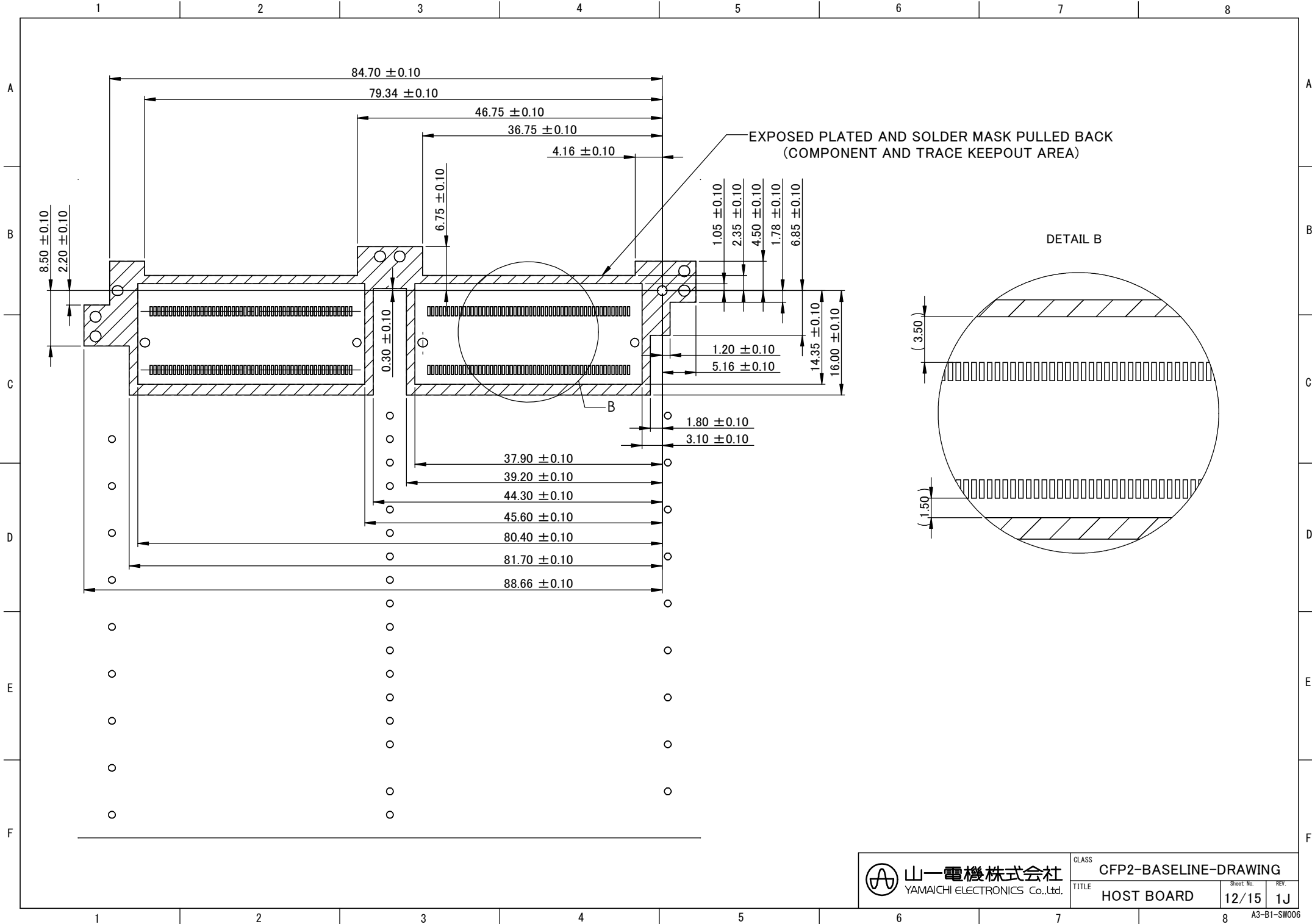
90.25 (GANGED PITCH)

NOTE  
1. THIS DRAWING SHOWS SIDE BY SIDE APPLICATION.



CLASS	CFP2-BASELINE-DRAWING	
TITLE	HOST BOARD	Sheet No.
	SIDE BY SIDE	REV.
	11/15	1J

1 2 3 4 5 6 7 8

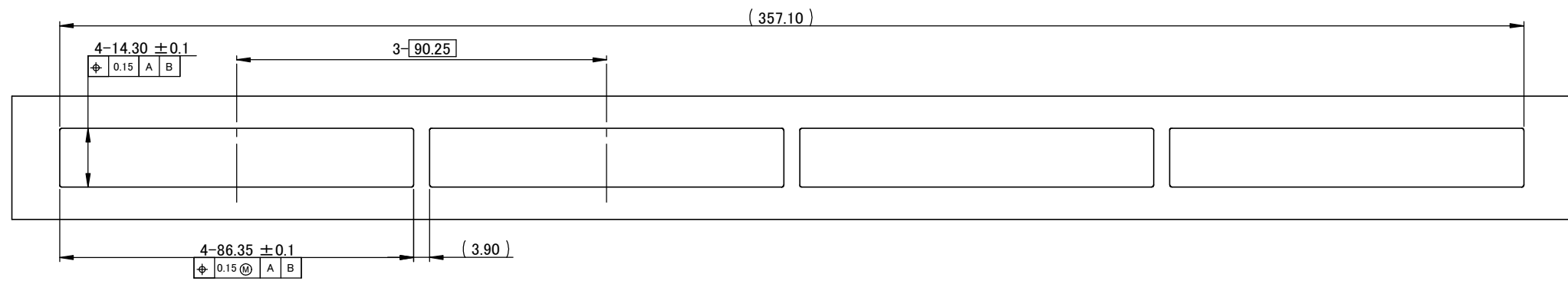
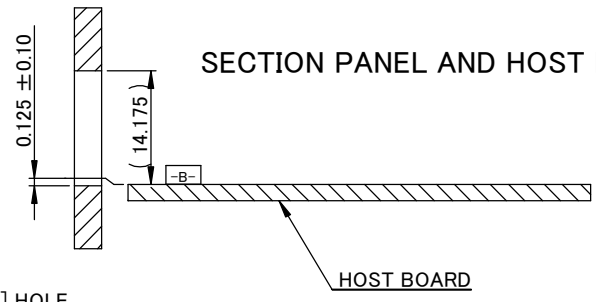
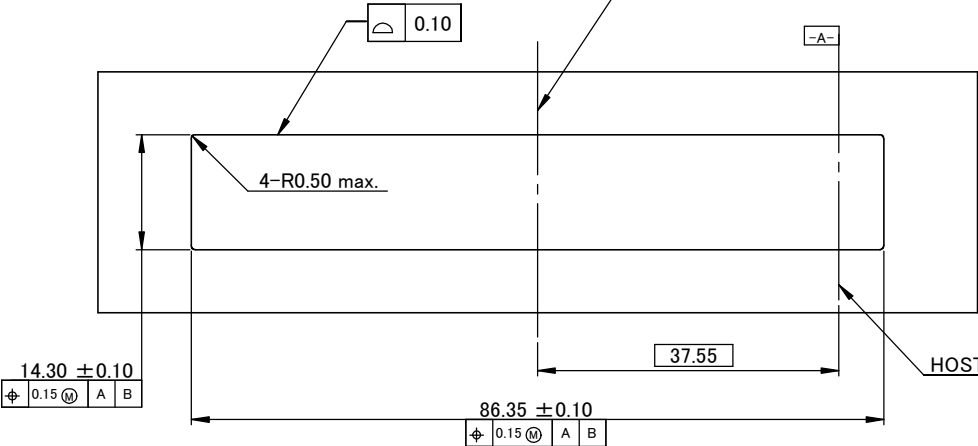



1 2 3 4 5 6 7 8

A B C D E F

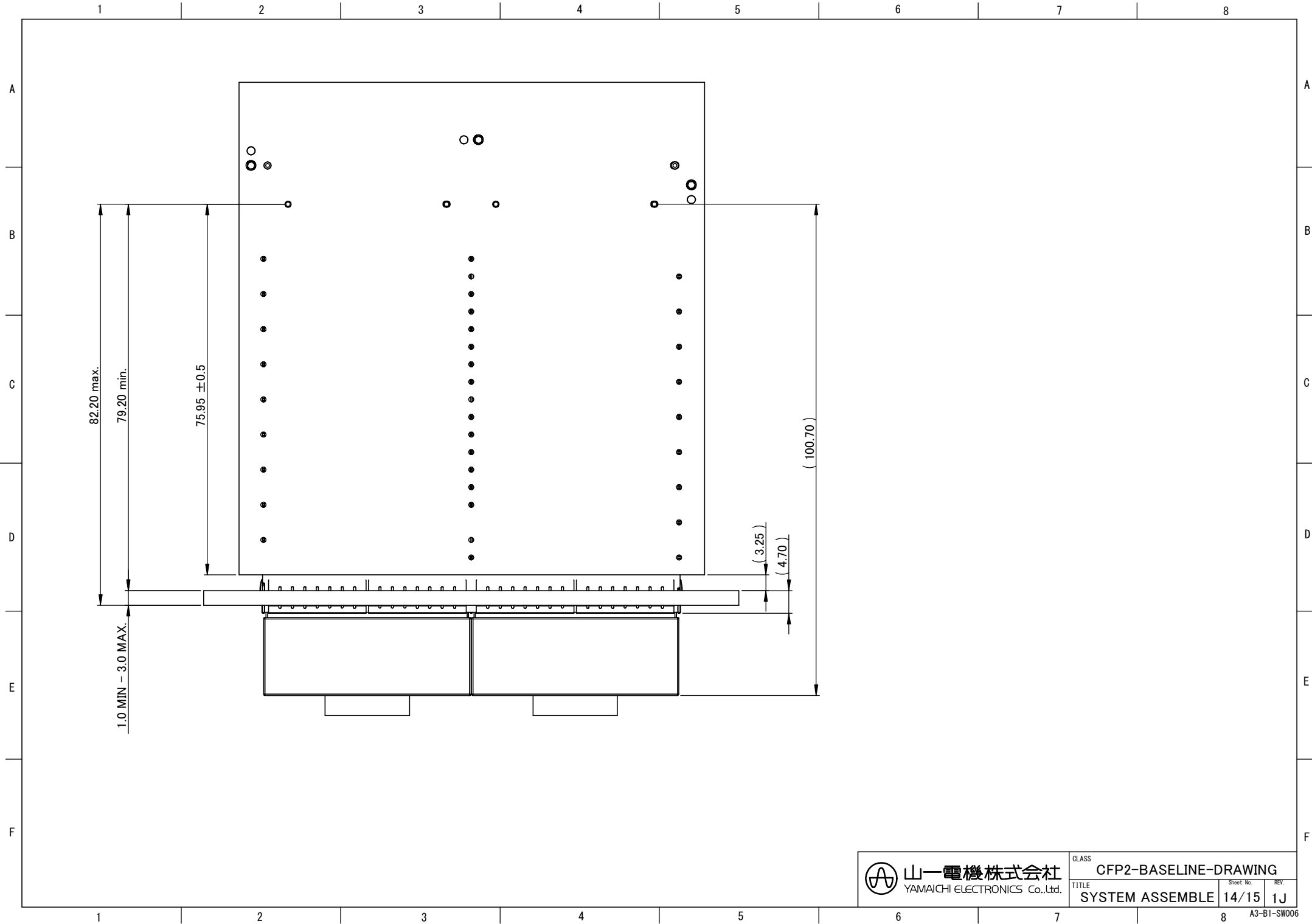
PANEL THICKNESS: 1.0 - 3.0

PANEL OPENING IS LOCATED FROM HOST BOARD [-A-] HOLE



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	TITLE	SYSTEM PANEL	Sheet No. 13/15 REV. 1J

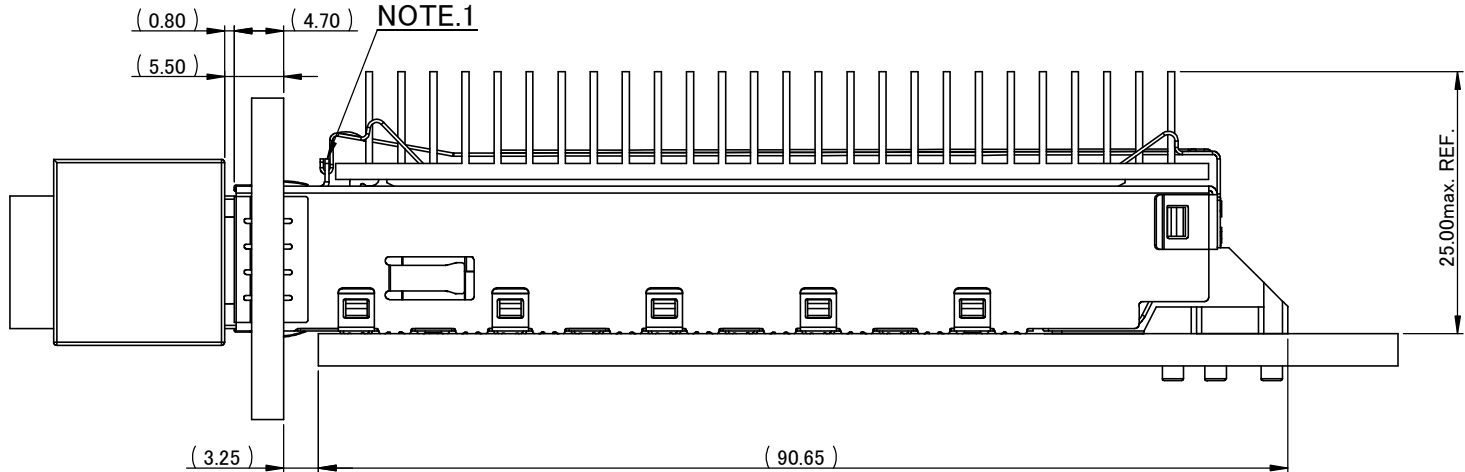
A3-B1-SW006



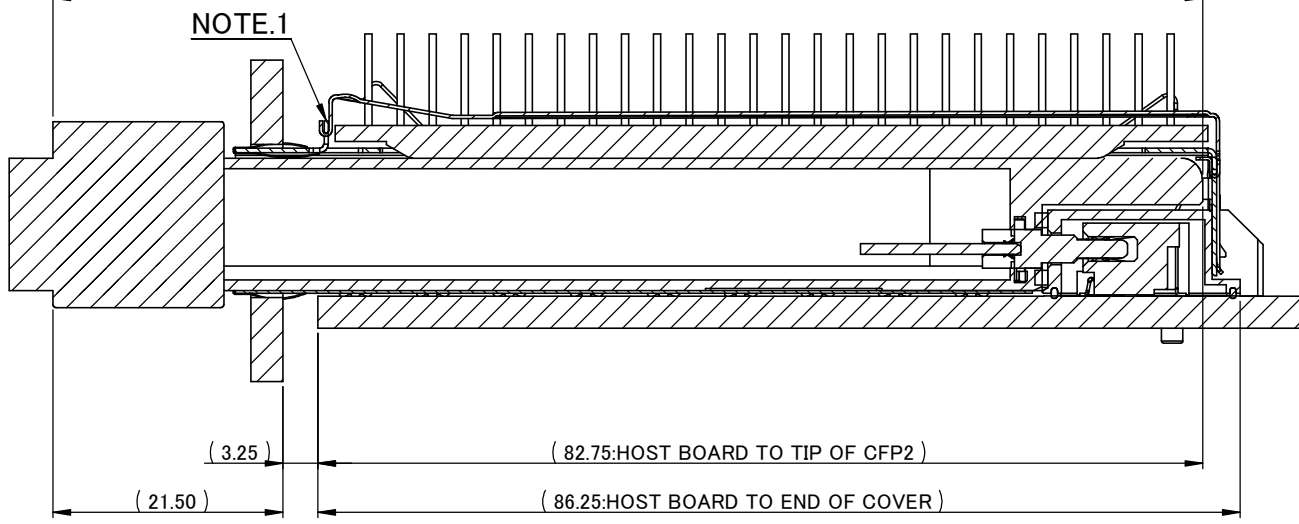
1 2 3 4 5 6 7 8

A  
B  
C  
D  
E  
F


A  
B  
C  
D  
E  
F



SECTION OF CENTER  
107.50 (LENGTH OF MODULE)



**NOTE**  
1. CAGE LOCK IS OPTIONAL. WITHOUT THE CAGE LOCK, A DIFFERENT HEATSINK DESIGN IS REQUIRED AS THE ONE SHOWN WILL NOT WORK.

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	TITLE SYSTEM ASSEMBLE	Sheet No. 15/15

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1 2 3 4 5 6 7 8